

High Linearity Silicon Germanium Bipolar RF Transistor

Data Sheet

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RF & Protection Devices

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BFP650, High Linearity Silicon Germanium Bipolar RF Transistor

Page	Subjects (changes since previous revision)
	This data sheet replaces the revision from 2010-10-22. The product itself has not been changed and the device characteristics remain unchanged. Only the product description and information available in the data sheet have been expanded and updated.

Revision History: 2012-09-13, Revision 1.1

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Product Brief

1 Product Brief

The BFP650 is a high linearity wideband NPN bipolar RF transistor. The device is based on Infineon's reliable high volume silicon germanium carbon (SiGe:C) heterojunction bipolar technology. The collector design supports voltages up to V_{CEO} = 4 V and currents up to I_{C} = 150 mA. With its high linearity at currents as low as 30 mA the device supports energy efficient designs. The typical transition frequency is approximately 42 GHz, hence the device offers high power gain at frequencies up to 5 GHz in amplifier applications. the device is housed in an easy to use plastic package with visible leads.

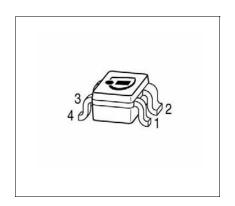






2 Features

- Linear low noise driver amplifier for RF frontends up to 5 GHz based on Infineon's reliable, high volume SiGe:C wafer technology
- Output compression point OP_{1dB} = 17 dBm at 70 mA, 3 V, 2.4 GHz, 50 Ω system
- Output 3rd order intermodulation point OIP_3 = 30 dBm at 70 mA, 3 V, 2.4 GHz, 50 Ω system
- Maximum available gain $G_{\rm ma}$ = 17.5 dB at 70 mA, 3 V, 2.4 GHz
- Minimum noise figure NF_{min} = 1 dB at 30 mA, 3 V, 2.4 GHz
- Easy to use Pb-free (RoHS compliant) and halogen-free standard package with visible leads
- Qualification report according to AEC-Q101 available





Application Examples

Driver amplifier

- ISM bands 434 and 868 MHz
- 1.9 GHz cordless phones
- CATV LNA

Transmitter driver amplifier

• 2.4 GHz WLAN / Bluetooth, 2.4 / 3.5 GHz WiMAX

Output stage LNA for active antennas

- TV, GPS, SDARS
- 2.4 / 5 GHz WLAN
- 2.4 / 3.5 / 5 GHz WiMAX, etc

Suitable for 5 - 10.5 GHz oscillators

Attention: ESD (Electrostatic discharge) sensitive device, observe handling precautions

Product Name	Package		Marking			
BFP650	SOT343	1 = B	2 = E	3 = C	4 = E	R5s



3 Maximum Ratings

Parameter	Symbol		Values	Unit	Note / Test Condition
		Min.	Max.		
Collector emitter voltage	V_{CEO}				Open base
		_	4.0	V	<i>T</i> _A = 25 °C
		_	3.7	V	<i>T</i> _A = -55 °C
Collector emitter voltage	V _{CES}	_	13	V	E-B short circuited
Collector base voltage	V _{CBO}	_	13	V	Open emitter
Emitter base voltage	V_{EBO}	-	1.2	V	Open collector
Collector current	I _C	-	150	mA	_
Base current	IB	_	10	mA	_
Total power dissipation ¹⁾	P _{tot}	-	500	mW	$T_{ m S} \leq$ 78 °C
Junction temperature	T_{J}	-	150	°C	_
Storage temperature	T _{Stg}	-55	150	°C	_
4)	1	· ' ·			

Table 3-1Maximum Ratings at $T_A = 25 \degree C$ (unless otherwise specified)

1) $T_{\rm S}$ is the soldering point temperature. $T_{\rm S}$ is measured on the emitter lead at the soldering point of the pcb.

Attention: Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit.



4 Thermal Characteristics

Table 4-1 Thermal Resistance

Parameter	Symbol	Values			Unit	Note / Test Condition	
		Min.	Тур.	Max.			
Junction - soldering point ¹⁾	R _{thJS}	-	140	-	K/W	-	

1)For the definition of R_{thJS} please refer to Application Note AN077 (Thermal Resistance Calculation)

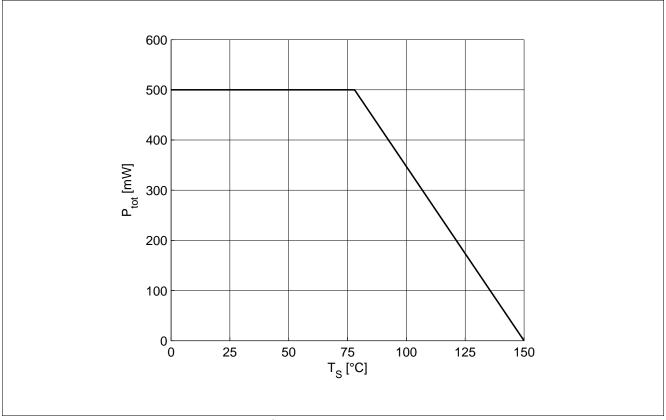


Figure 4-1 Total Power Dissipation $P_{tot} = f(T_s)$



5 Electrical Characteristics

5.1 DC Characteristics

Table 5-1 DC Characteristics at $T_A = 25 \text{ °C}$

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Collector emitter breakdown voltage	$V_{\rm (BR)CEO}$	4	4.5	_	V	$I_{\rm C}$ = 3 mA, $I_{\rm B}$ = 0
						Open base
Collector emitter leakage current	I _{CES}	-	0.1	1	μA	V _{CE} = 13 V, V _{BE} = 0
		-	1	40	nA	$V_{\rm CE}$ = 5 V, $V_{\rm BE}$ = 0
						E-B short circuited
Collector base leakage current	I _{CBO}	-	1	40	nA	V _{CB} = 5 V, I _E = 0
						Open emitter
Emitter base leakage current	I _{EBO}	-	10	500	nA	$V_{\rm EB}$ = 0.5 V, $I_{\rm C}$ = 0
						Open collector
DC current gain	h_{FE}	100	170	250		$V_{\rm CE}$ = 3 V, $I_{\rm C}$ = 70 mA
						Pulse measured

5.2 General AC Characteristics

Table 5-2 General AC Characteristics at $T_A = 25 \text{ °C}$

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Transition frequency	f _T	31	42	-	GHz	V_{CE} = 3 V, I_{C} = 70 mA, f = 1 GHz
Collector base capacitance	C _{CB}	-	0.26	0.4	pF	V_{CB} = 3 V, V_{BE} = 0 V f = 1 MHz Emitter grounded
Collector emitter capacitance	C _{CE}	-	0.45	-	pF	V_{CE} = 3 V, V_{BE} = 0 V f = 1 MHz Base grounded
Emitter base capacitance	C _{EB}	-	1.3	-	pF	$V_{\rm EB}$ = 0.5 V, $V_{\rm CB}$ = 0 V f = 1 MHz Collector grounded



5.3 Frequency Dependent AC Characteristics

Measurement setup is a test fixture with Bias T's in a 50 Ω system, T_A = 25 °C

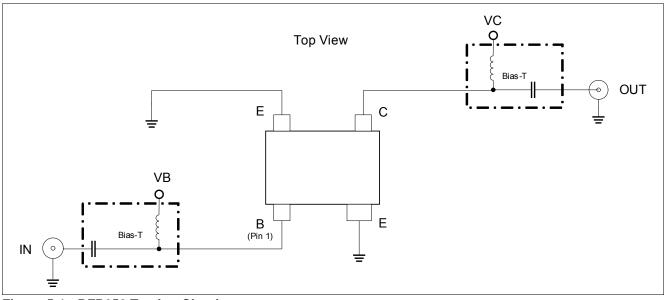


Figure 5-1 BFP650 Testing Circuit

Table 5-3	AC Characteristics,	$V_{CE} = 3 \text{ V}, f = 150 \text{ MHz}$
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Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Maximum power gain					dB	
High linearity operation point	$G_{\sf ms}$	-	35.5	_		<i>I</i> _C = 30 mA
Class A operation point	$G_{\sf ms}$	-	38	-		<i>I</i> _C = 70 mA
Transducer gain					dB	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
High linearity operation point	S ₂₁	-	35	-		<i>I</i> _C = 30 mA
Class A operation point	S ₂₁	-	37.5	-		<i>I</i> _C = 70 mA
Minimum noise figure					dB	$Z_{\rm S} = Z_{\rm opt}$
Minimum noise figure	NF_{\min}	-	0.75	-		<i>I</i> _C = 30 mA
Associated gain	G_{ass}	-	32	-		<i>I</i> _C = 30 mA
Linearity					dBm	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
1 dB gain compression point	OP _{1dB}	-	16.5	-		<i>I</i> _C = 70 mA
3rd order intercept point	OIP ₃	-	29.5	-		<i>I</i> _C = 70 mA



Electrical Characteristics

Table 5-4 AC Characteristics, V_{CE} = 3 V, f = 450 MHz

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Maximum power gain					dB	
High linearity operation point	$G_{\sf ms}$	_	30	_		<i>I</i> _C = 30 mA
Class A operation point	$G_{\sf ms}$	_	31.5	_		<i>I</i> _C = 70 mA
Transducer gain					dB	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
High linearity operation point	S ₂₁	_	29	-		<i>I</i> _C = 30 mA
Class A operation point	S ₂₁	_	29.5	_		<i>I</i> _C = 70 mA
Minimum noise figure					dB	$Z_{\rm S} = Z_{\rm opt}$
Minimum noise figure	NF_{\min}	_	0.75	_		<i>I</i> _C = 30 mA
Associated gain	G_{ass}	_	29.5	_		<i>I</i> _C = 30 mA
Linearity					dBm	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
1 dB gain compression point	OP _{1dB}	-	16.5	-		<i>I</i> _C = 70 mA
3rd order intercept point	OIP ₃	_	30	-		<i>I</i> _C = 70 mA

Table 5-5 AC Characteristics, V_{CE} = 3 V, f = 900 MHz

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Maximum power gain					dB	
High linearity operation point	$G_{\sf ms}$	_	25.5	_		I _C = 30 mA
Class A operation point	$G_{\sf ms}$	_	26.5	_		<i>I</i> _C = 70 mA
Transducer gain					dB	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
High linearity operation point	S ₂₁	_	23.5	-		I _C = 30 mA
Class A operation point	S ₂₁	_	24	_		I _C = 70 mA
Minimum noise figure					dB	$Z_{\rm S} = Z_{\rm opt}$
Minimum noise figure	$NF_{\sf min}$	_	0.8	_		I _C = 30 mA
Associated gain	G_{ass}	_	24.5	_		I _C = 30 mA
Linearity					dBm	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
1 dB gain compression point	OP _{1dB}	-	17	_		<i>I</i> _C = 70 mA
3rd order intercept point	OIP ₃	-	31	-		I _C = 70 mA



Electrical Characteristics

Table 5-6 AC Characteristics, V_{CE} = 3 V, f = 1.5 GHz

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Maximum power gain					dB	
High linearity operation point	$G_{\sf ms}$	_	22	_		I _C = 30 mA
Class A operation point	$G_{\sf ms}$	_	22.5	-		<i>I</i> _C = 70 mA
Transducer gain					dB	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
High linearity operation point	S ₂₁	_	19	_		I _C = 30 mA
Class A operation point	S ₂₁	_	19.5	_		I _C = 70 mA
Minimum noise figure					dB	$Z_{\rm S} = Z_{\rm opt}$
Minimum noise figure	NF _{min}	_	0.85	_		$I_{\rm C} = 30 {\rm mA}$
Associated gain	G_{ass}	_	20.5	_		I _C = 30 mA
Linearity					dBm	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
1 dB gain compression point	OP _{1dB}	_	17	_		<i>I</i> _C = 70 mA
3rd order intercept point	OIP ₃	_	31	-		<i>I</i> _C = 70 mA

Table 5-7 AC Characteristics, V_{CE} = 3 V, f = 1.9 GHz

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Maximum power gain					dB	
High linearity operation point	G_{ma}	-	20.5	_		<i>I</i> _C = 30 mA
Class A operation point	$G_{\sf ms}$	-	20	_		<i>I</i> _C = 70 mA
Transducer gain					dB	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
High linearity operation point	S ₂₁	-	17	_		I _C = 30 mA
Class A operation point	S ₂₁	-	17.5	_		I _C = 70 mA
Minimum noise figure					dB	$Z_{\rm S} = Z_{\rm opt}$
Minimum noise figure	NF_{min}	-	0.95	_		I _C = 30 mA
Associated gain	G_{ass}	-	17.5	_		I _C = 30 mA
Linearity					dBm	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
1 dB gain compression point	OP _{1dB}	-	17	-		<i>I</i> _C = 70 mA
3rd order intercept point	OIP ₃	-	30.5	-		<i>I</i> _C = 70 mA



Electrical Characteristics

Table 5-8 AC Characteristics, V_{CE} = 3 V, f = 2.4 GHz

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Maximum power gain					dB	
High linearity operation point	G_{ma}	_	18	_		I _C = 30 mA
Class A operation point	$G_{\sf ma}$	_	17.5	-		<i>I</i> _C = 70 mA
Transducer gain					dB	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
High linearity operation point	S ₂₁	_	14.5	_		I _C = 30 mA
Class A operation point	S ₂₁	_	15	_		I _C = 70 mA
Minimum noise figure					dB	$Z_{\rm S} = Z_{\rm opt}$
Minimum noise figure	NF _{min}	_	1	_		I _C = 30 mA
Associated gain	G_{ass}	_	15	_		I _C = 30 mA
Linearity					dBm	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
1 dB gain compression point	OP _{1dB}	_	17	_		<i>I</i> _C = 70 mA
3rd order intercept point	OIP ₃	_	30	-		<i>I</i> _C = 70 mA

Table 5-9 AC Characteristics, V_{CE} = 3 V, f = 3.5 GHz

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
Maximum power gain					dB	
High linearity operation point	G_{ma}	_	14	_		<i>I</i> _C = 30 mA
Class A operation point	$G_{\sf ma}$	_	14.5	-		<i>I</i> _C = 70 mA
Transducer gain					dB	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
High linearity operation point	S ₂₁	_	11	-		I _C = 30 mA
Class A operation point	S ₂₁	_	11.5	_		<i>I</i> _C = 70 mA
Minimum noise figure					dB	$Z_{\rm S}$ = $Z_{\rm opt}$
Minimum noise figure	NF _{min}	_	1.2	_		<i>I</i> _C = 30 mA
Associated gain	G_{ass}	_	11.5	_		<i>I</i> _C = 30 mA
Linearity					dBm	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
1 dB gain compression point	OP _{1dB}	-	17	-		<i>I</i> _C = 70 mA
3rd order intercept point	OIP ₃	-	30	-		<i>I</i> _C = 70 mA

15



Parameter	Symbol		Value	s	Unit	Note / Test Condition
		Min.	Тур.	Max.		
Maximum power gain					dB	
High linearity operation point	G_{ma}	_	10.5	-		<i>I</i> _C = 30 mA
Class A operation point	G_{ma}	_	10.5	-		<i>I</i> _C = 70 mA
Transducer gain					dB	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
High linearity operation point	S ₂₁	_	6.5	-		<i>I</i> _C = 30 mA
Class A operation point	S ₂₁	-	7	-		<i>I</i> _C = 70 mA
Minimum noise figure					dB	$Z_{\rm S} = Z_{\rm opt}$
Minimum noise figure	NF_{min}	-	1.6	-		<i>I</i> _C = 30 mA
Associated gain	G_{ass}	-	8.5	-		<i>I</i> _C = 30 mA
Linearity					dBm	$Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω
1 dB gain compression point	OP _{1dB}	_	16.5	-		<i>I</i> _C = 70 mA
3rd order intercept point	OIP ₃	-	29.5	-		<i>I</i> _C = 70 mA

Table 5-10 AC Characteristics, V_{CE} = 3 V, f = 5.5 GHz

Notes

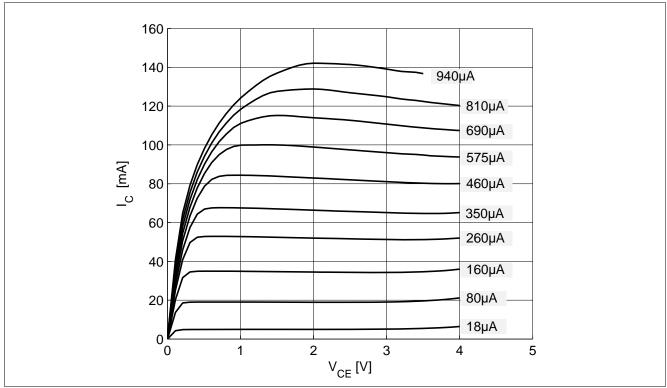
- 2. In order to get the NF_{min} values stated in this chapter the test fixture losses have been subtracted from all measured result.
- 3. OIP_3 value depends on termination of all intermodulation frequency components. Termination used for this measurement is 50 Ω from 0.2 MHz to 12 GHz.

^{1.} AC parameter limits verified by random sampling.



Electrical Characteristics







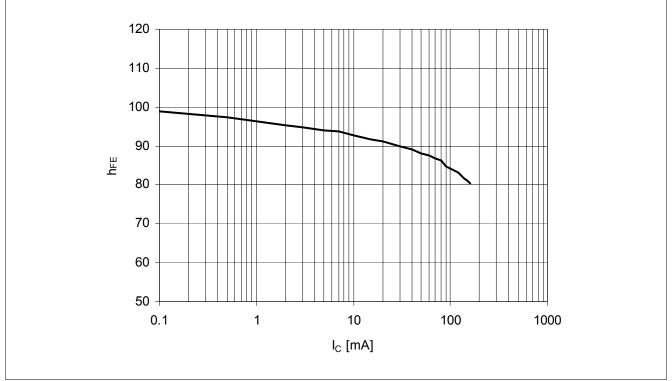


Figure 5-3 DC Current Gain $h_{FE} = f(I_C), V_{CE} = 3 V$



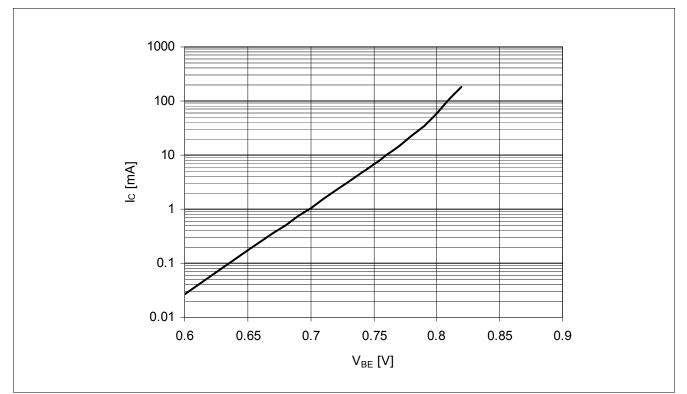


Figure 5-4 Collector Current vs. Base Emitter Voltage $I_{C} = f(V_{BE}), V_{CE} = 2 V$

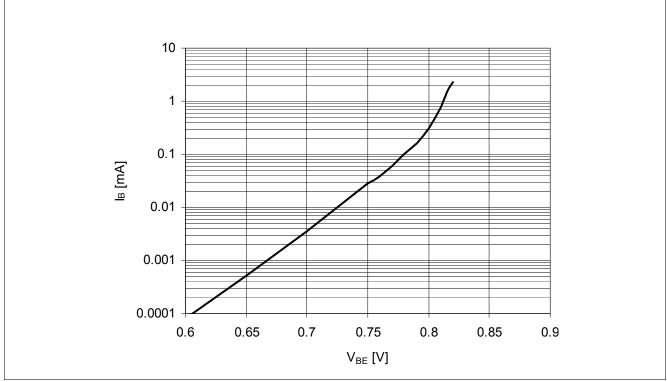


Figure 5-5 Base Current vs. Base Emitter Forward Voltage $I_{\rm B} = f(V_{\rm BE}), V_{\rm CE} = 2 \text{ V}$

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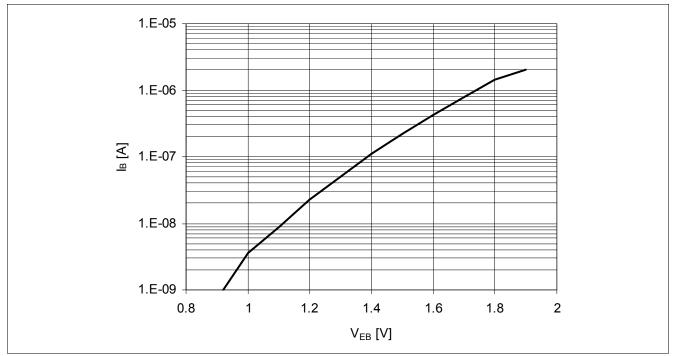


Figure 5-6 Base Current vs. Base Emitter Reverse Voltage $I_{\rm B}$ = $f(V_{\rm EB})$, $V_{\rm CE}$ = 2 V



Electrical Characteristics

5.5 Characteristic AC Diagrams

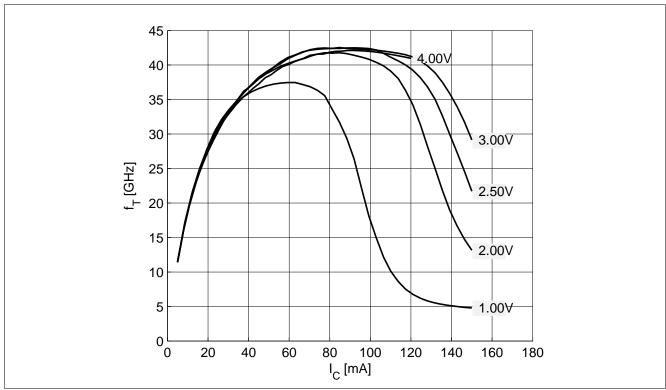


Figure 5-7 Transition Frequency $f_T = f(I_C), f = 1$ GHz, V_{CE} = Parameter in V

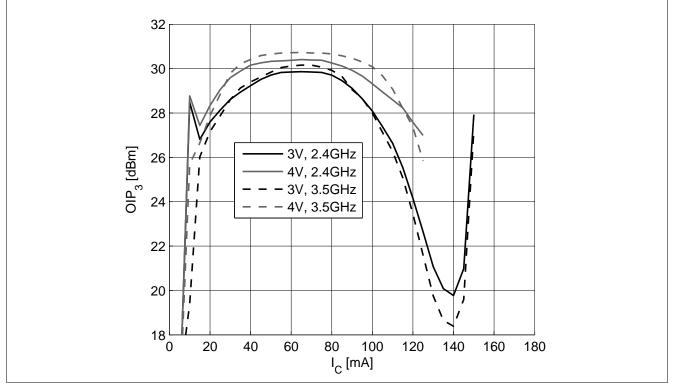
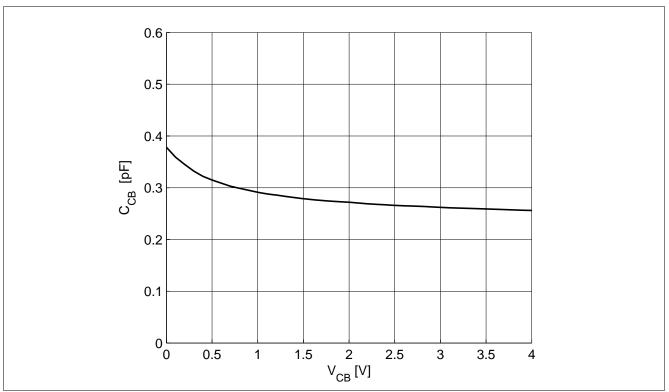


Figure 5-8 3rd Order Intercept Point $OIP_3 = f(I_C)$, $Z_S = Z_L = 50 \Omega$, V_{CE} , f = Parameters



Electrical Characteristics





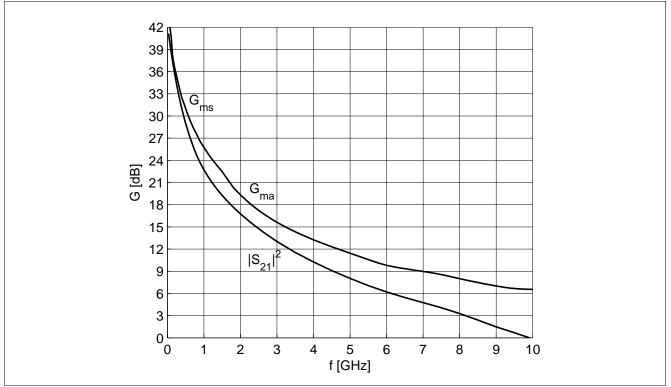


Figure 5-10 Gain G_{ma} , G_{ms} , $IS_{21}I^2 = f(f)$, $V_{CE} = 3 \text{ V}$, $I_C = 70 \text{ mA}$



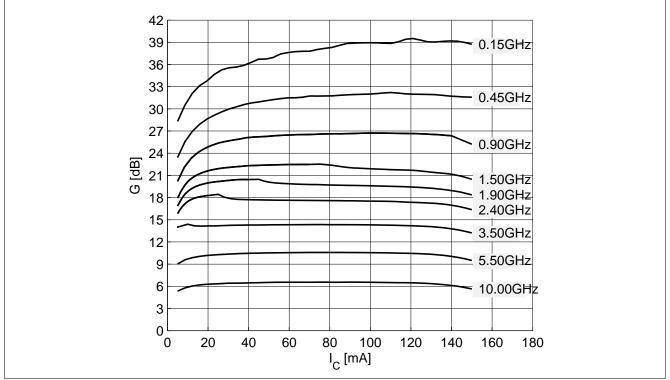


Figure 5-11 Maximum Power Gain $G_{max} = f(I_C)$, $V_{CE} = 3 V$, f = Parameter in GHz

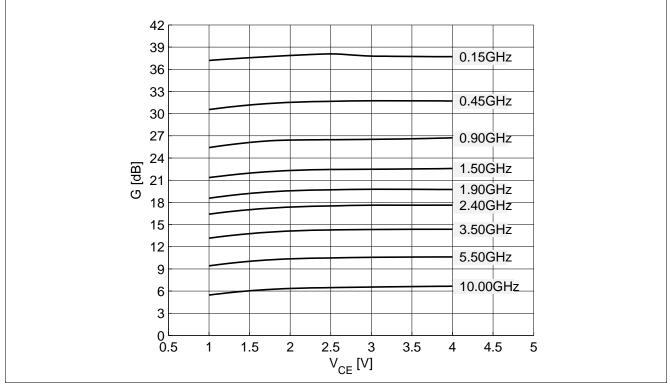


Figure 5-12 Maximum Power Gain $G_{max} = f(V_{CE})$, $I_{C} = 70 \text{ mA}$, f = Parameter in GHz



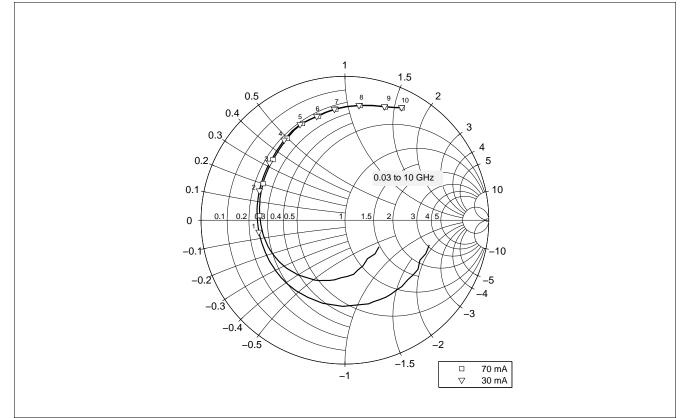


Figure 5-13 Input Matching $S_{11} = f(f)$, $V_{CE} = 3 \text{ V}$, $I_C = 30 / 70 \text{ mA}$

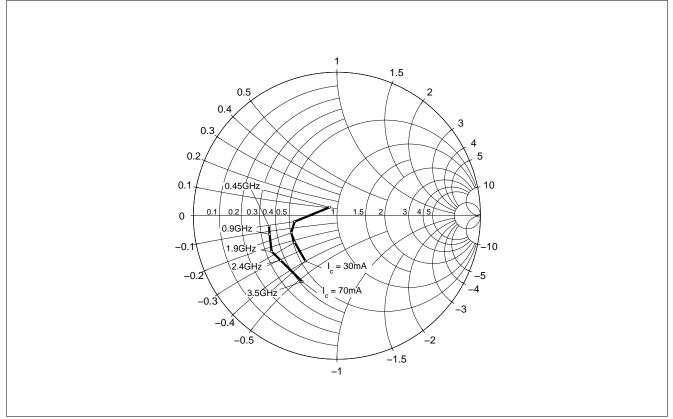


Figure 5-14 Source Impedance for Minimum Noise Figure _{opt} = f(f), V_{CE} = 3 V, I_{C} = 30 / 70 mA



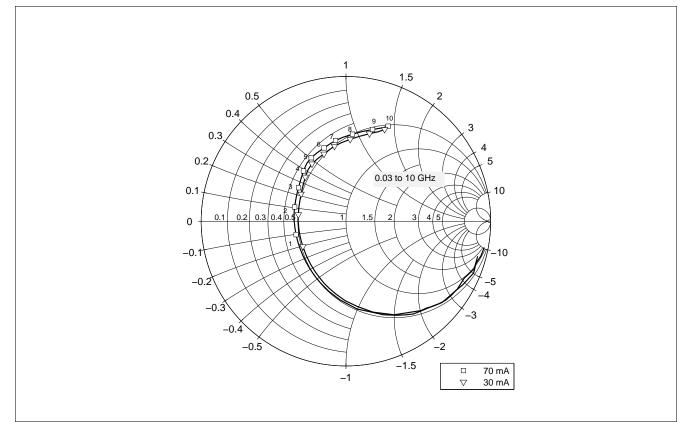


Figure 5-15 Output Matching $S_{22} = f(f)$, $V_{CE} = 3 \text{ V}$, $I_{C} = 30 / 70 \text{ mA}$

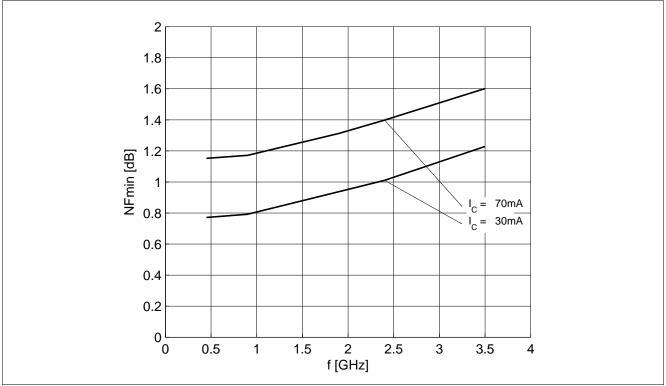


Figure 5-16 Noise Figure $NF_{min} = f(f)$, $V_{CE} = 3 \text{ V}$, $I_C = 30 \text{ / } 70 \text{ mA}$, $Z_S = Z_{opt}$



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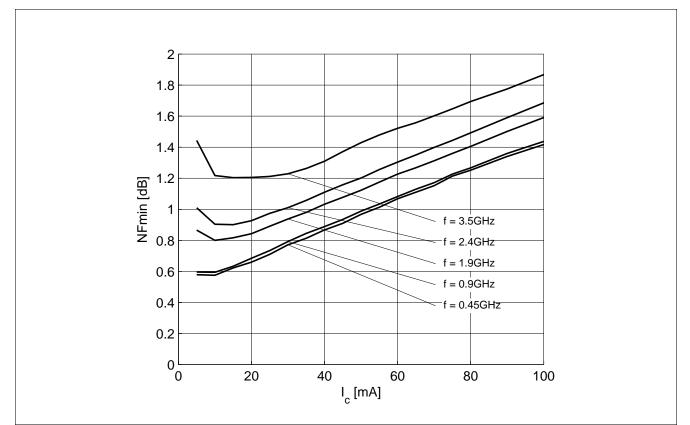


Figure 5-17 Noise Figure $NF_{min} = f(I_{C}), V_{CE} = 3 V, Z_{S} = Z_{opt}$ = Parameter in GHz

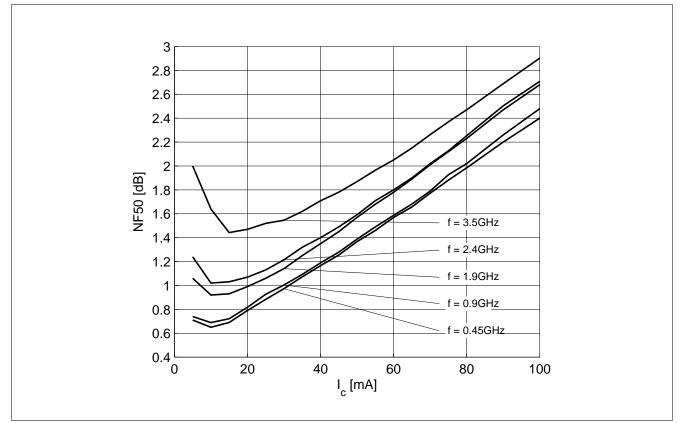


Figure 5-18 Noise Figure $NF_{50} = f(I_{C}), V_{CE} = 3 V, Z_{S} = 50 \Omega, f = Parameter in GHz$





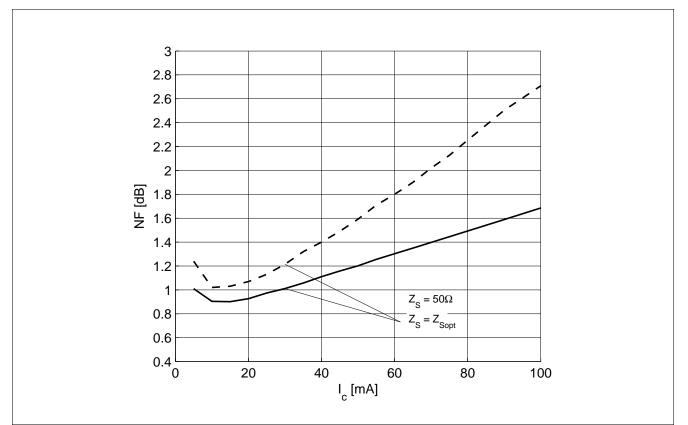


Figure 5-19 Comparison Noise Figure $NF_{50} / NF_{min} = f(I_C), V_{CE} = 3 V, f = 2.4 GHz$

Note: The curves shown in this chapter have been generated using typical devices but shall not be considered as a guarantee that all devices have identical characteristic curves. $T_A = 25$ °C.



Simulation Data

6 Simulation Data

For the SPICE Gummel Poon (GP) model as well as for the S-parameters (including noise parameters) please refer to our internet website: www.infineon.com/rf.models. Please consult our website and download the latest versions before actually starting your design.

You find the BFP650 SPICE GP model in the internet in MWO- and ADS-format, which you can import into these circuit simulation tools very quickly and conveniently. The model already contains the package parasitic and is ready to use for DC- and high frequency simulations. The terminals of the model circuit correspond to the pin configuration of the device.

The model parameters have been extracted and verified up to 10 GHz using typical devices. The BFP650 SPICE GP model reflects the typical DC- and RF-performance within the limitations which are given by the SPICE GP model itself.

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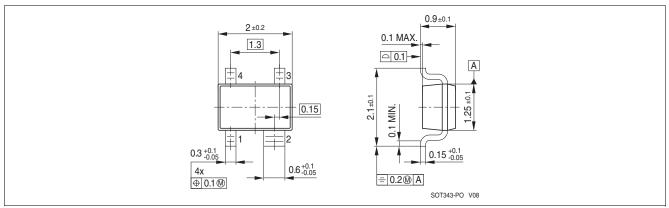


Figure 7-1 Package Outline

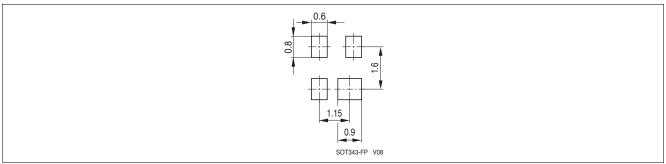


Figure 7-2 Package Footprint

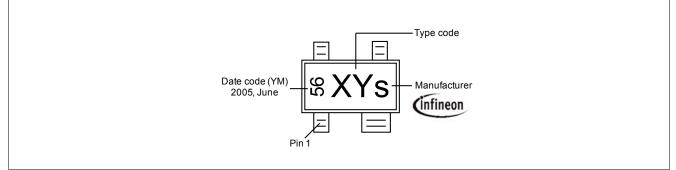


Figure 7-3 Marking Example (Marking BFP650: R5s)

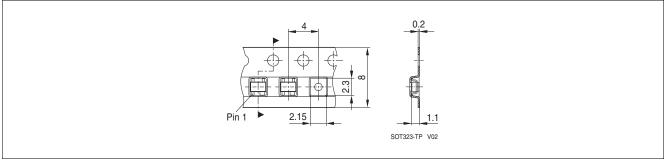


Figure 7-4 Tape dimensions

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